

## 100V P-Channel MOSFETs

### General Description

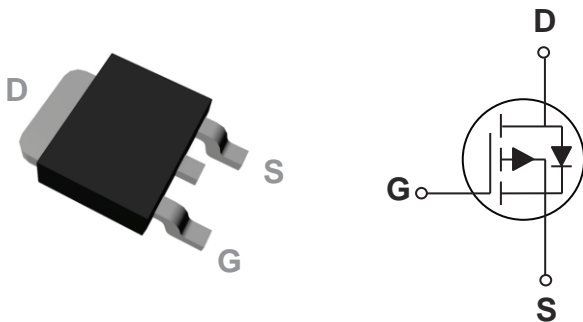
These P-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior switching performance, and withstand high energy pulse in the avalanche and commutation mode. These devices are well suited for high efficiency fast switching applications.

BVDSS	R <sub>DS(ON)</sub>	I <sub>D</sub>
-100V	95mΩ	-18A

### Features

- -100V,-18A, R<sub>DS(ON)</sub> 95mΩ @V<sub>GS</sub> = -10V
- V<sub>GS</sub> Guarantee ±25V
- Improved dv/dt capability
- Fast switching
- Green Device Available

### TO-252 Pin Configuration



### Applications

- Networking
- Load Switch
- LED applications

### Absolute Maximum Ratings (T<sub>c</sub>=25 °C unless otherwise noted)

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	-100	V
V <sub>GS</sub>	Gate-Source Voltage	±25	V
I <sub>D</sub>	Drain Current – Continuous (T <sub>c</sub> =25°C)	-18	A
	Drain Current – Continuous (T <sub>c</sub> =100°C)	-11.4	A
I <sub>DM</sub>	Drain Current – Pulsed <sup>1</sup>	-72	A
EAS	Single Pulse Avalanche Energy <sup>2</sup>	54	mJ
IAS	Single Pulse Avalanched Current <sup>2</sup>	-33	A
P <sub>D</sub>	Power Dissipation (T <sub>c</sub> =25°C)	73.5	W
	Power Dissipation – Derate above 25°C	0.59	W/°C
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C

### Thermal Characteristics

Symbol	Parameter	Typ.	Max.	Unit
R <sub>θJC</sub>	Thermal Resistance Junction to Case	---	1.7	°C/W
R <sub>θJA</sub>	Thermal Resistance Junction to ambient	---	62	°C/W



# FTK0903D

## Electrical Characteristics ( $T_J=25^\circ\text{C}$ , unless otherwise noted)

### Off Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250\mu A$	-100	---	---	V
$\Delta BV_{DSS}/\Delta T_J$	$BV_{DSS}$ Temperature Coefficient	Reference to $25^\circ\text{C}$ , $I_D=-1mA$	---	0.06	---	V/ $^\circ\text{C}$
$I_{DSS}$	Drain-Source Leakage Current	$V_{DS}=-100V, V_{GS}=0V, T_J=25^\circ\text{C}$	---	---	-1	$\mu A$
		$V_{DS}=-80V, V_{GS}=0V, T_J=125^\circ\text{C}$	---	---	-10	$\mu A$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS}=\pm 25V, V_{DS}=0V$	---	---	$\pm 100$	nA

### On Characteristics

$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=-10V, I_D=-6A$	---	75	95	m $\Omega$
		$V_{GS}=-4.5V, I_D=-3A$	---	80	110	m $\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS}=V_{DS}, I_D=-250\mu A$	-1.2	-1.6	-2.2	V
$\Delta V_{GS(th)}$	$V_{GS(th)}$ Temperature Coefficient		---	-4.46	---	mV/ $^\circ\text{C}$

### Dynamic and switching Characteristics

$Q_g$	Total Gate Charge <sup>3, 4</sup>	$V_{DS}=-50V, V_{GS}=-10V, I_D=-6A$	---	40.4	70	nC
$Q_{gs}$	Gate-Source Charge <sup>3, 4</sup>		---	7.7	15	
$Q_{gd}$	Gate-Drain Charge <sup>3, 4</sup>		---	6.6	13	
$T_{d(on)}$	Turn-On Delay Time <sup>3, 4</sup>	$V_{DD}=-30V, V_{GS}=-10V, R_G=6\Omega$ $I_D=-1A$	---	27	54	ns
$T_r$	Rise Time <sup>3, 4</sup>		---	12	24	
$T_{d(off)}$	Turn-Off Delay Time <sup>3, 4</sup>		---	150	300	
$T_f$	Fall Time <sup>3, 4</sup>		---	45	90	
$C_{iss}$	Input Capacitance	$V_{DS}=-30V, V_{GS}=0V, F=1MHz$	---	2250	3900	pF
$C_{oss}$	Output Capacitance		---	130	250	
$C_{riss}$	Reverse Transfer Capacitance		---	90	180	
$R_g$	Gate resistance		$V_{GS}=0V, V_{DS}=0V, F=1MHz$	---	10	

### Drain-Source Diode Characteristics and Maximum Ratings

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
$I_S$	Continuous Source Current	$V_G=V_D=0V$ , Force Current	---	---	-18	A
$I_{SM}$	Pulsed Source Current		---	---	-36	A
$V_{SD}$	Diode Forward Voltage	$V_{GS}=0V, I_S=-1A, T_J=25^\circ\text{C}$	---	---	-1.2	V
$t_{rr}$	Reverse Recovery Time	$V_R=-100V, I_S=-10A$	---	50	---	ns
$Q_{rr}$	Reverse Recovery Charge	$di/dt=100A/\mu s, T_J=25^\circ\text{C}$	---	60	---	nC

Note :

1. Repetitive Rating : Pulsed width limited by maximum junction temperature.
2.  $V_{DD}=-25V, V_{GS}=-10V, L=0.1mH, I_{AS}=-33A, R_G=25\Omega$ , Starting  $T_J=25^\circ\text{C}$ .
3. The data tested by pulsed, pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.

## ELECTRICAL CHARACTERISTICS CURVES

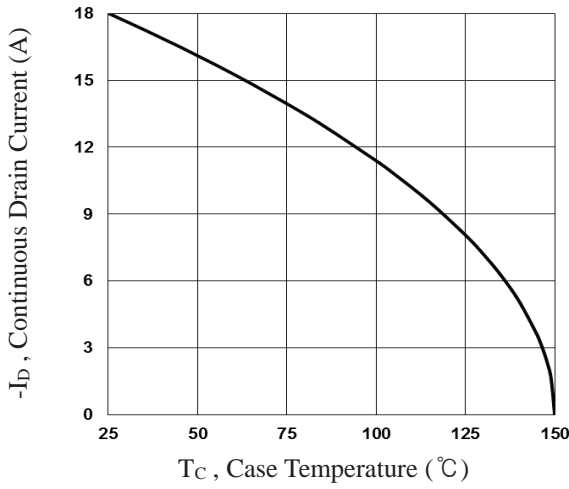


Fig.1 Continuous Drain Current vs.  $T_c$

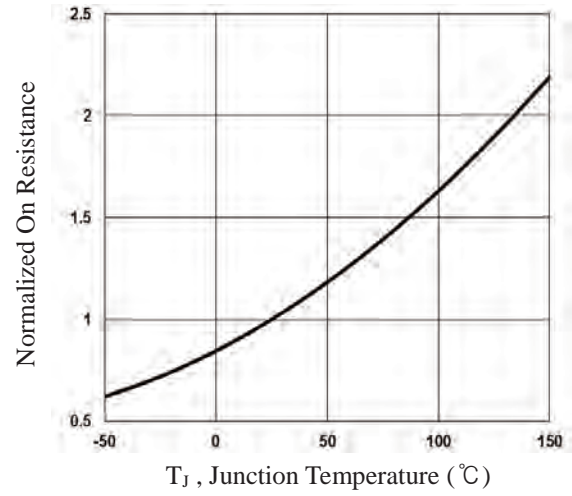


Fig.2 Normalized  $R_{DS(on)}$  vs.  $T_j$

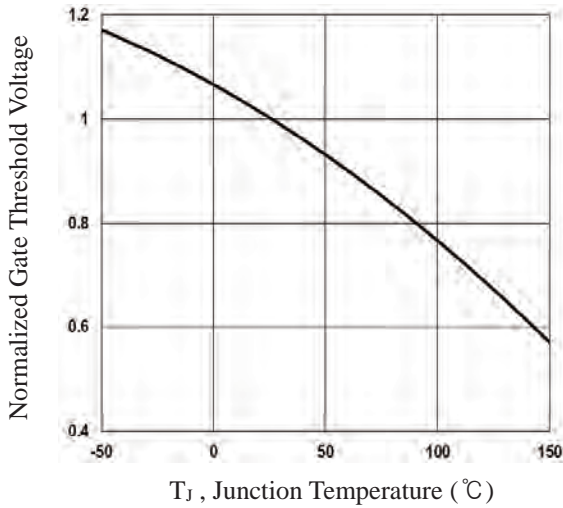


Fig.3 Normalized  $V_{th}$  vs.  $T_j$

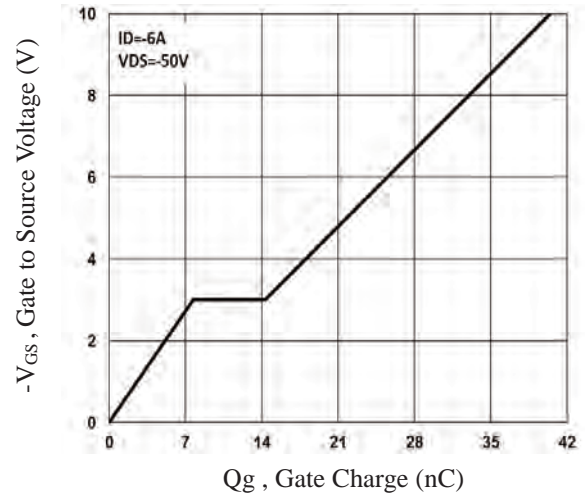


Fig.4 Gate Charge Waveform

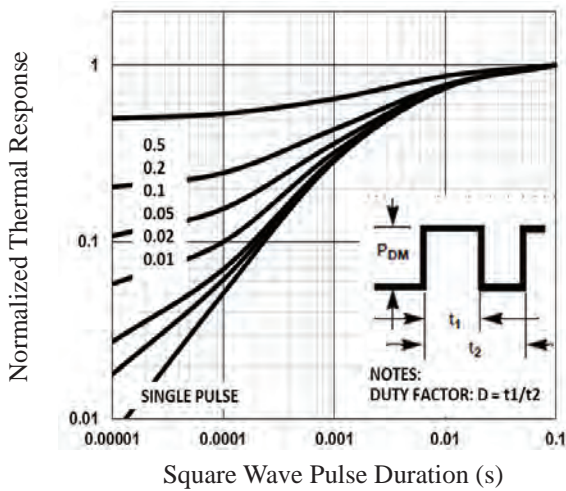


Fig.5 Normalized Transient Impedance

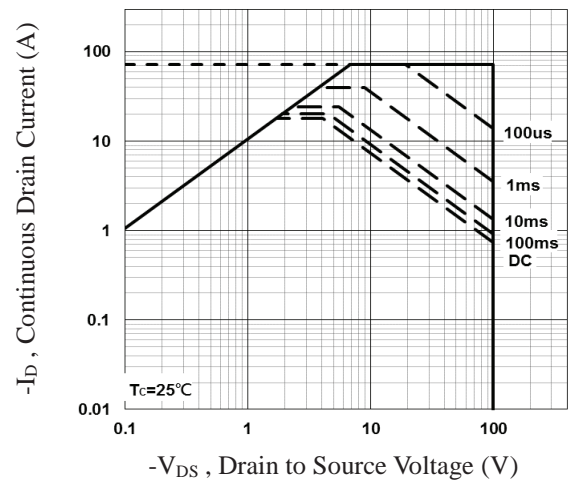


Fig.6 Maximum Safe Operation Area

## ELECTRICAL CHARACTERISTICS CURVES (Con.)

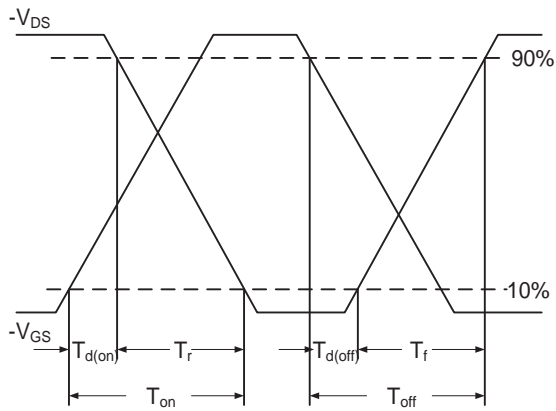


Fig.7 Switching Time Waveform

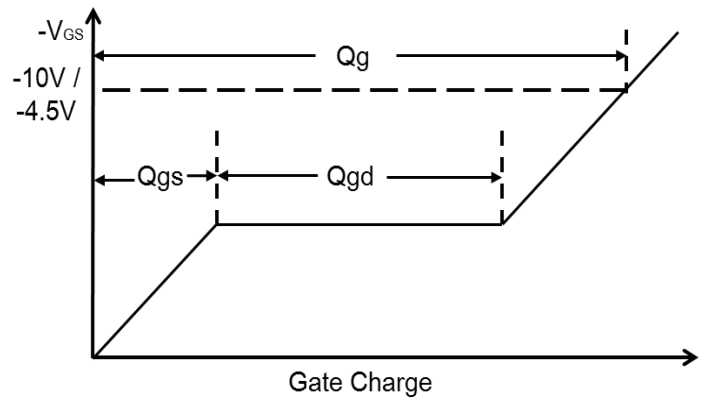
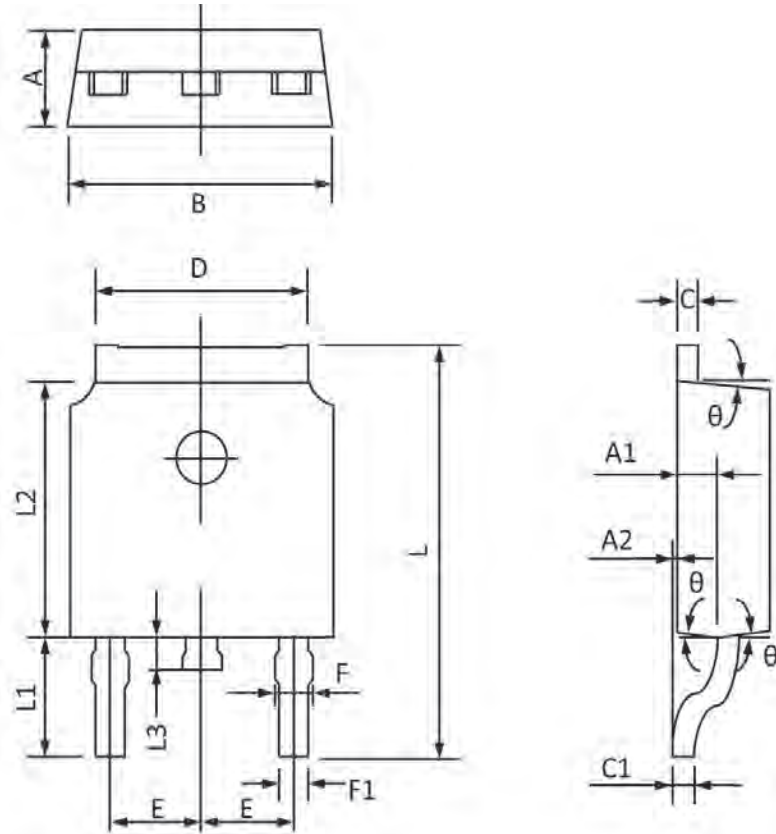


Fig.8 Gate Charge Waveform

## TO-252 PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	MAX	MIN	MAX	MIN
A	2.450	2.150	0.096	0.085
A1	1.200	0.910	0.047	0.036
A2	0.150	0.000	0.006	0.000
B	6.800	6.300	0.268	0.248
C	0.580	0.350	0.023	0.014
C1	0.550	0.380	0.022	0.015
D	5.500	5.100	0.217	0.201
E	2.390	2.000	0.094	0.079
F	0.940	0.600	0.037	0.024
F1	0.860	0.500	0.034	0.020
L	10.400	9.400	0.409	0.370
L1	3.000	2.400	0.118	0.094
L2	6.200	5.300	0.244	0.209
L3	1.200	0.600	0.047	0.024
θ	9°	3°	9°	3°